# Extraction of *k*<sub>t2</sub> of film/wafer structure by conversion loss methods without acoustic losses in the substrate

ウェハー状態の圧電薄膜共振子の基板内音響損失を除いた変 換損 k2 導出法

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## 1. Introduction

According to the IEEE standard, the resonance-antiresonance method<sub>[1]</sub> for a self-standing film structure is recommended to determine  $k_{12}$  of the piezoelectric film. It is convenient and cost-effective to determine the  $k_{12}$  from the film/wafer structure (HBAR) or epitaxial wafers.  $k_{12}$  is underestimated due to the acoustic losses in the substrate in the conventional conversion loss (*CL*) method<sub>[2]</sub>, which can extract the  $k_{12}$  from HBAR.

In this study, we derived two *CL* methods: (i) the method subtracting the acoustic losses in the substrate, (ii) the method using electromagnetic signal including no acoustic losses.

# 2. Conventional CL method

The experimental CL of the resonator were determined from  $S_{11}$ , measured by a network analyzer. The inverse Fourier transform (IFFT) of  $S_{11}$  gives the impulse response in the time domain (Fig. 1). The impulse response includes multiple echo pulses reflected from the bottom surface of the substrate. The insertion loss (*IL*) can be obtained from the Fourier transform (FFT) of the first echo.

When the RF is applied to the piezoelectric layer, the generated bulk wave propagates and reflects in the substrate. As shown in **Fig. 2**, the *IL* includes five losses: (i) doubled the *CL* in the piezoelectric film ( $k_{12}$ ), (ii) electrode resistance  $R_s$ , (iii) inductance  $L_s$ , (iv) electrical impedance mismatch between measurement circuit and the resonator, (v) propagation loss, diffraction loss, and reflection loss. (ii), (iii), (iv) can be determined by using Mason's model. Therefore, the  $k_{12}$  can be extracted by comparing the experimental conversion loss with the theoretical one simulated by Mason's model. However, (i)  $k_{12}$  is underestimated because the *IL* includes (v) losses.

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#### 3. Method subtracting the acoustic losses

#### 3.1 Method

The *IL* of the second echo includes (i), (ii), (iii), (iv), (v) and additional losses (v), (vi) energy of the first echo returning to the network analyzer (Fig. 1). Therefore, the difference between the IL of the second echo and one of the first echo corresponds to impedance (v)+(vi).Characteristic  $Z_0$ of measurement circuit was changed on the calculation to make electrical impedance mismatch between measurement circuit and the resonator. Thus, (v) can be estimated because (vi) does not return to the network analyzer. Finally, (v) losses can be excluded from the IL of the first echo. This method can avoid the  $k_{12}$  underestimation in the conventional method.

## 3.2 Results and Discussions

We compared the literature value of propagation loss with (v) loss in our proposed method by Mason's model including propagation loss (Fig. 4). The loss for the literature value and that estimated from the present method ( $Z_0 = 1500 \Omega$ ) agreed well, indicating the method is accurate.



Fig. 4 Propagation loss in our proposed method and literature value.

## 4. Method using electromagnetic signal

#### 4.1 Method

As shown in **Fig. 5**, the electromagnetic signal includes four losses: (i) *CL* between electrical energy and mechanical energy, and (ii), (iii), (iv) as above. (ii) can be excluded by connecting the experimental impedance with the negative electrode resistance  $-R_s$  in the model.



Fig. 5 Losses in the new *CL* method.

4.2 Results and Discussions

ScAlN film was grown on Ti bottom electrode/silica glass substrate. We compared  $k_{12}$  of the films before (mirror Ra:1 nm) and after (rough Ra:110 nm) roughened the substrate bottom to change acoustic loss of the substrate.  $k_{12}$  were determined using the conventional and new *CL* method. As shown in **Fig. 6**,  $k_{12}$  in the case of Ra:1 nm and 110 nm derived from the conventional method showed different values due to the reflection loss in the substrate bottom surface. As shown in **Fig.** 

7,  $k_{12}$  derived from the new method showed the same values and are larger than  $k_{12}$  in the conventional method because the electromagnetic signal includes no the acoustic losses in the substrate. Our new method can avoid the  $k_{12}$  underestimation in the conventional method.



Fig. 6 Experimental *CL* in the conventional *CL* method.



## 5. Conclusion

As shown in **Table. I**,  $k_{12}$  is underestimated due to the acoustic losses in the substrate in the conventional method. Our new two methods can avoid the  $k_{12}$  underestimation.

Method	ScAlN	ScAlN
	/Si (Rough)	/Si (mirror)
Conventional	16.9 %	18.8 %
CL method		
Method subtracting	22.4 %	22.4 %
the acoustic losses		
Method using	22.5 %	22.5 %
electromagnetic signal		

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#### References

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